

**PRXS300HF12DFQ1****Description**

The PRXS300HF12DFQ1 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips and SiC Diode designed for the applications such as Motor drives and Renewable energy.

**Features**

- Blocking voltage:1200V
- $R_{DS(on)} = 6.4m\Omega$
- Low thermal resistance with Si<sub>3</sub>N<sub>4</sub> AMB
- 175°C maximum junction temperature
- 62mm half bridge module
- Low Switching Losses

**Applications**

- Motor Drives
- Vehicle Fast Chargers
- Renewable energy
- UPS

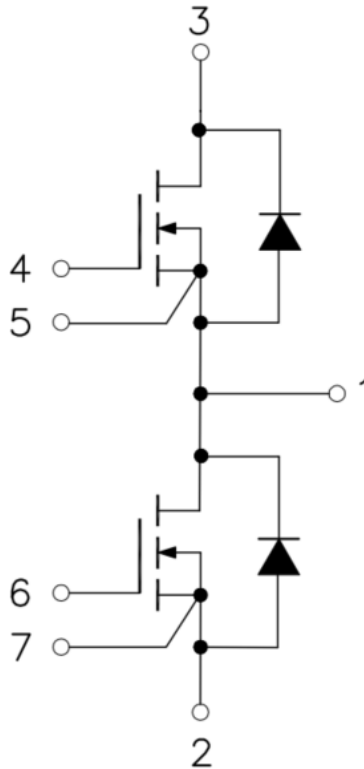
**Circuit Diagram**

Figure 1. Out drawing & circuit diagram for PRXS300HF12DFQ1



**PRXS300HF12DFQ1**  
**1200V/300A Half Bridge SiC MOSFET Module**

**Module**

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, f =50Hz, t =1min	4.0	kV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 10	mm
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	>400	-
Module lead resistance, terminals – chip	T <sub>C</sub> =25°C	0.6	mΩ
Mounting torque for module mounting	M6	4 to 6	Nm
Weight	-	320	g

**Maximum Ratings** (T<sub>j</sub> =25°C unless otherwise specified)

Symbol	Parameter	Condition	Ratings	Unit
V <sub>DSS</sub>	Drain-Source Voltage	G-S Short	1200	V
V <sub>DS nom</sub>	Continuous Operating DC Voltage	Not include surge voltage	1100	V
V <sub>GSS</sub>	Gate-Source Voltage	D-S Short, AC frequency ≥ 1Hz, Note1	-10 to 25	V
I <sub>DS</sub>	DC Continuous Drain Current	T <sub>C</sub> =25°C, V <sub>GS</sub> =20V	360	A
I <sub>DS</sub>	DC Continuous Drain Current	T <sub>C</sub> =80°C, V <sub>GS</sub> =20V	280	A
I <sub>DP</sub>	Drain Pulse Current, Peak	T <sub>C</sub> =25°C, Less than 1ms, Note2	600	A
I <sub>F</sub>	Forward Current	T <sub>C</sub> =25°C, with ON signal	350	A
I <sub>F</sub>	Forward Current	T <sub>C</sub> =80°C, with ON signal	260	A
I <sub>FRM</sub>	Pulse Forward Current	T <sub>C</sub> =25°C, Less than 1ms, Note2	600	A
P <sub>tot</sub>	Total Power Dissipation	T <sub>C</sub> =25°C	1666	W
T <sub>jmax</sub>	Max Junction Temperature	-	175	°C
T <sub>sg</sub>	Storage Temperature	-	-40 to 125	°C

Note1: Recommended Operating Value, +20V/-5V ,+18V/-5V, +15V/-4V

Note2: Pulse width limited by maximum junction temperature

**PRXS300HF12DFQ1**  
**1200V/300A Half Bridge SiC MOSFET Module**

**MOSFET Electrical characteristics** ( $T_j = 25^\circ\text{C}$  unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=3mA$	1200	-	-	V	
$I_{DSS}$	Zero gate voltage drain Current	$V_{DS}=1200V, V_{GS}=0V$	-	3	-	$\mu A$	
$V_{GS(th)}$	Gate-source threshold Voltage	$I_D=60mA, V_{DS}=V_{GS}$	$T_j=25^\circ\text{C}$	1.8	2.5	4.0	V
			$T_j=175^\circ\text{C}$	-	1.6	-	V
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=20V, V_{DS}=0V$	$T_j=25^\circ\text{C}$	-	60	600	nA
$R_{DS(on)}$ (Chip)	Static drain-source On-state resistance	$I_D=300A$ $V_{GS}=20V$	$T_j=25^\circ\text{C}$	-	6.4	-	$m\Omega$
			$T_j=175^\circ\text{C}$	-	12.3	-	$m\Omega$
		$I_D=300A$ $V_{GS}=18V$	$T_j=25^\circ\text{C}$	-	7.2	-	$m\Omega$
			$T_j=175^\circ\text{C}$	-	12.9	-	$m\Omega$
$V_{DS(on)}$ (Chip)	Static drain-source On-state Voltage	$I_D=300A$ $V_{GS}=20V$	$T_j=25^\circ\text{C}$	-	1.9	-	V
			$T_j=175^\circ\text{C}$	-	3.7	-	V
		$I_D=300A$ $V_{GS}=18V$	$T_j=25^\circ\text{C}$	-	2.2	-	V
			$T_j=175^\circ\text{C}$	-	3.9	-	V
$C_{iss}$	Input Capacitance	$V_D=800V, V_{GS}=0V, f=100kHz,$ $V_{AC}=25mV$	-	19.0	-	nF	
$C_{oss}$	Output Capacitance		-	1.08	-	nF	
$C_{rss}$	Reverse transfer Capacitance		-	0.11	-	nF	
$Q_G$	Total gate charge	$V_{DD}=800V, I_D=150A, V_{GS}=+20/-5V$	-	660	-	nC	
$R_{Gint}$	Internal Gate Resistance	$T_j=25^\circ\text{C}$	-	2.0	-	$\Omega$	
$t_{d(on)}$	Turn-on delay time	$V_{DD}=600V$ $I_D=300A$ $V_{GS}=+18/-5V$ $R_{G(on)}=3.3\Omega$ $R_{G(off)}=3.3\Omega$ Inductive load switching operation	$T_j=25^\circ\text{C}$	-	42	-	ns
			$T_j=150^\circ\text{C}$	-	38	-	
$t_r$	Rise time		$T_j=25^\circ\text{C}$	-	36	-	ns
			$T_j=150^\circ\text{C}$	-	32	-	
$t_{d(off)}$	Turn-off delay time		$T_j=25^\circ\text{C}$	-	32	-	ns
			$T_j=150^\circ\text{C}$	-	43	-	
$t_f$	Fall time		$T_j=25^\circ\text{C}$	-	17	-	ns
			$T_j=150^\circ\text{C}$	-	21	-	
$E_{on}$	Turn-on power dissipation		$T_j=25^\circ\text{C}$	-	5.6	-	mJ
			$T_j=150^\circ\text{C}$	-	7.9	-	
$E_{off}$	Turn-off power dissipation	$T_j=25^\circ\text{C}$	-	1.6	-	mJ	
		$T_j=150^\circ\text{C}$	-	2.8	-		
$R_{th(j-c)}$	FET Thermal Resistance	Junction to Case	-	0.09	-	$^\circ\text{C}/W$	

**PRXS300HF12DFQ1**  
**1200V/300A Half Bridge SiC MOSFET Module**

**SiC SBD Electrical characteristics** ( $T_j = 25^\circ\text{C}$  unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
$V_F$	Diode Forward Voltage	$I_F = 300\text{A}, V_{GS} = -4\text{V}$	$T_j = 25^\circ\text{C}$	-	1.90	-	V
			$T_j = 175^\circ\text{C}$	-	3.35	-	
$t_{rr}$	Diode Reverse Recovery Time	$V_{RR} = 600\text{V}, I_D = 300\text{A}$	$T_j = 25^\circ\text{C}$	-	25	-	ns
			$T_j = 150^\circ\text{C}$	-	27	-	
$I_{RM}$	Peak reverse recovery Current	MOSFET side: $V_{GS} = +18/-5\text{V}$	$T_j = 25^\circ\text{C}$	-	115	-	A
			$T_j = 150^\circ\text{C}$	-	140	-	
$Q_{rr}$	Recovered charge	$R_{G(on)} = R_{G(off)} = 3.3\Omega$ Inductive load	$T_j = 25^\circ\text{C}$	-	1.9	-	$\mu\text{C}$
			$T_j = 150^\circ\text{C}$	-	2.6	-	
$E_{rr}$	Reverse recovered energy	switching operation	$T_j = 25^\circ\text{C}$	-	0.5	-	mJ
			$T_j = 150^\circ\text{C}$	-	1.3	-	
$R_{th(j-c)}$	Thermal Resistance, Junction to Case (Diode)		-	0.12	-	$^\circ\text{C/W}$	

**Test Conditions**

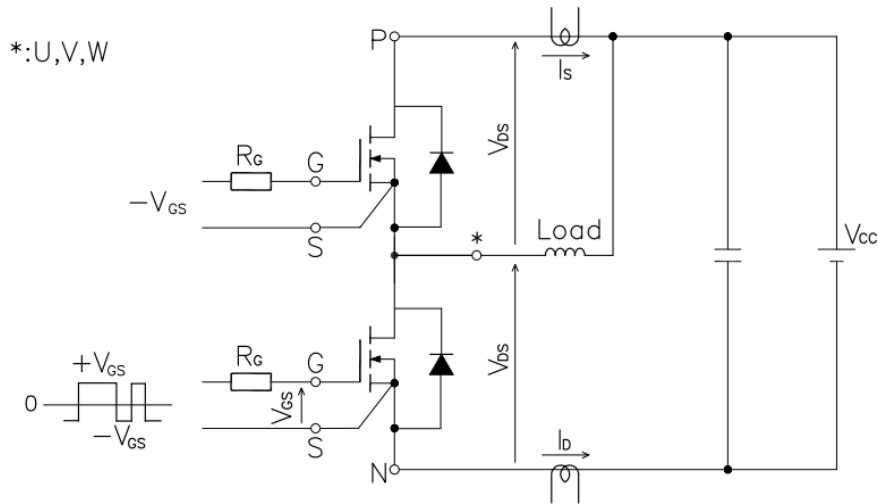


Figure 3. Switching time measure circuit

**PRXS300HF12DFQ1**  
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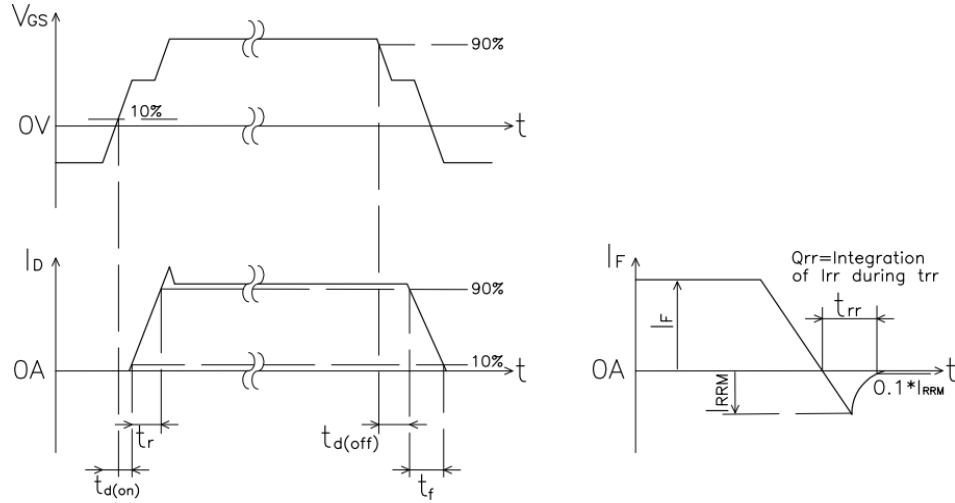
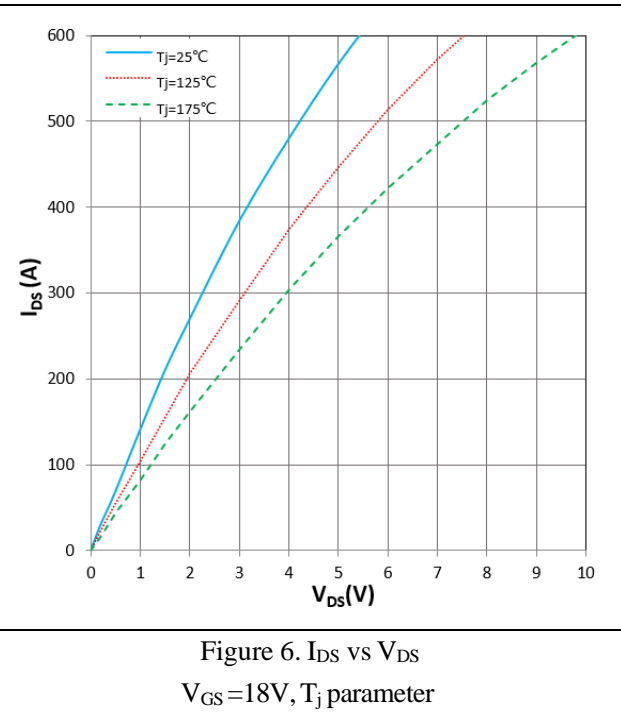
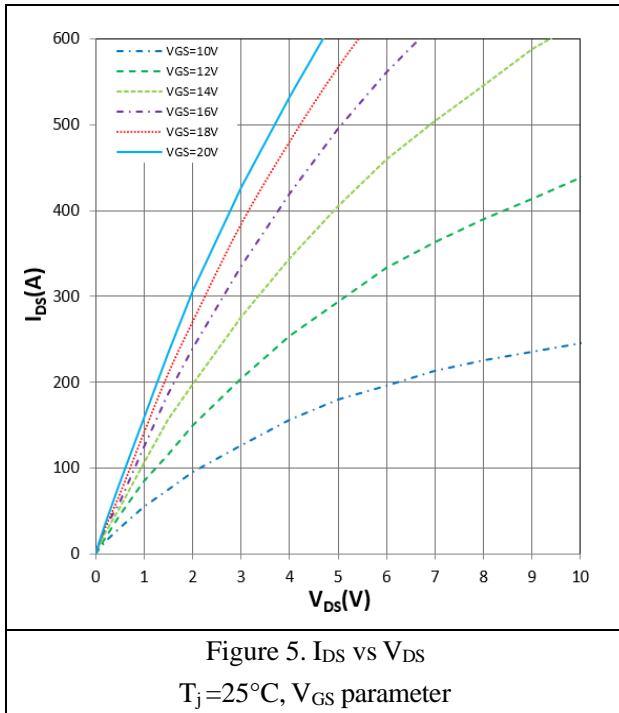


Figure 4. Switching time definition



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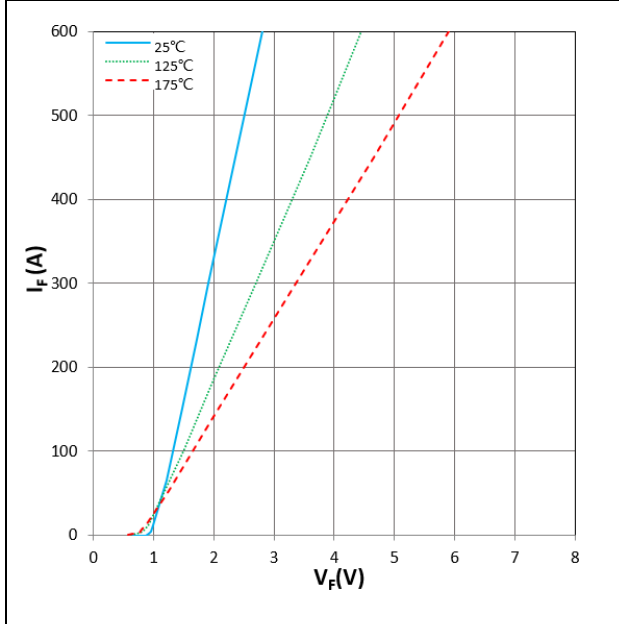


Figure 7.  $I_F$  vs  $V_F$   
 $V_{GS} = 0V$

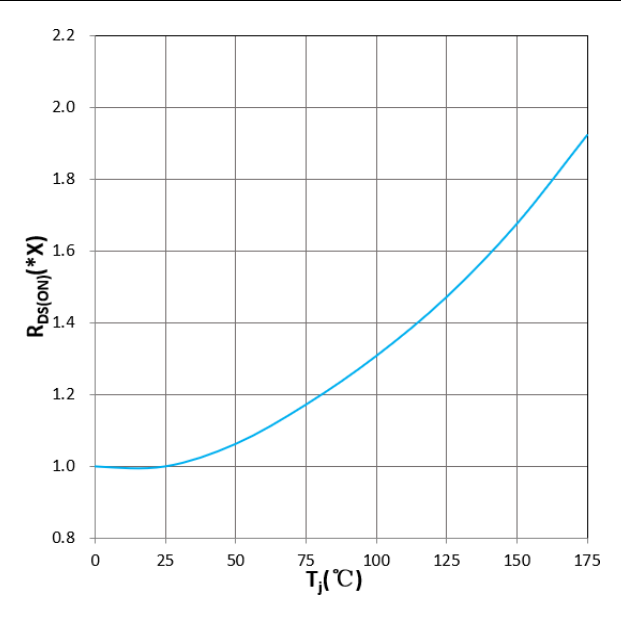


Figure 8.  $R_{DS(ON)}$  vs  $T_j$   
 $V_{GS} = +20V, I_D = 300A, 1.0X = 6.4m\Omega$

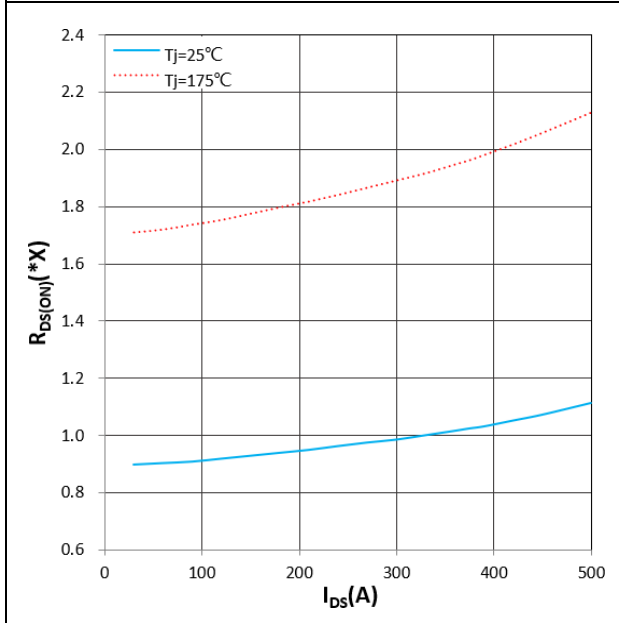


Figure 9.  $R_{DS(ON)}$  vs  $I_{DS}$   
 $T_j = 25^\circ C / 175^\circ C, V_{GS} = +20V, 1.0X = 6.4m\Omega$

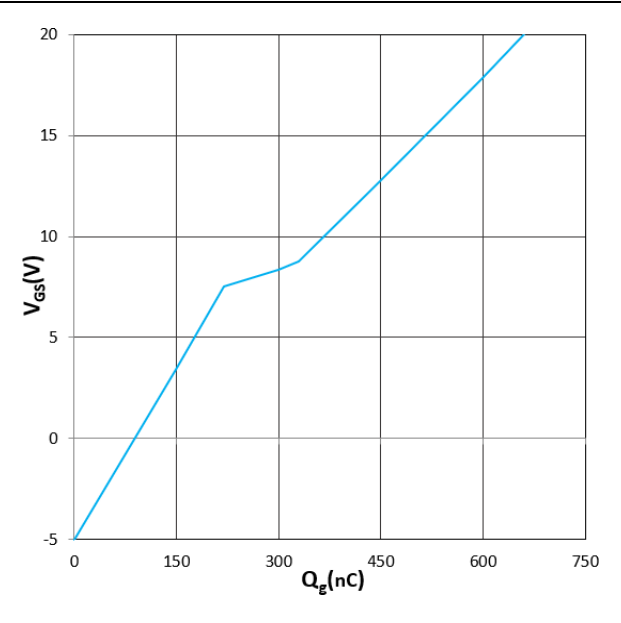


Figure 10.  $V_{GS}$  vs  $Q_g$   
 $T_j = 25^\circ C, V_{DS} = 800V, I_D = 150A$

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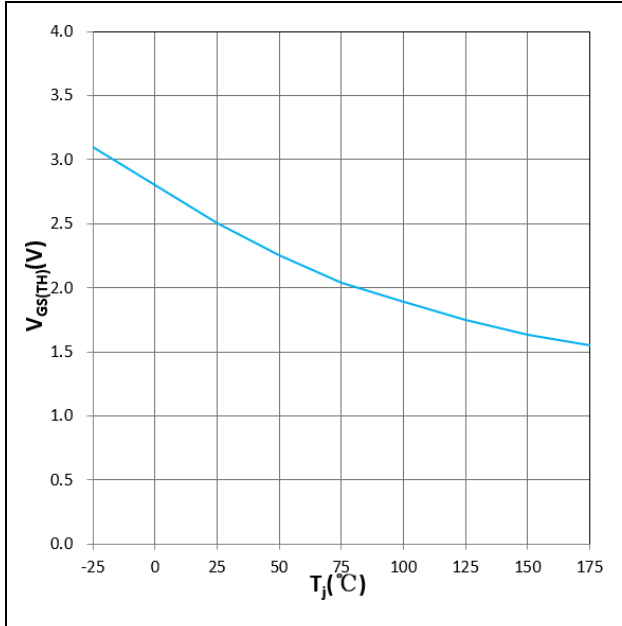


Figure 11.  $V_{GS(TH)}$  vs  $T_j$   
 $V_{GS} = V_{DS}$ ,  $I_D = 60mA$

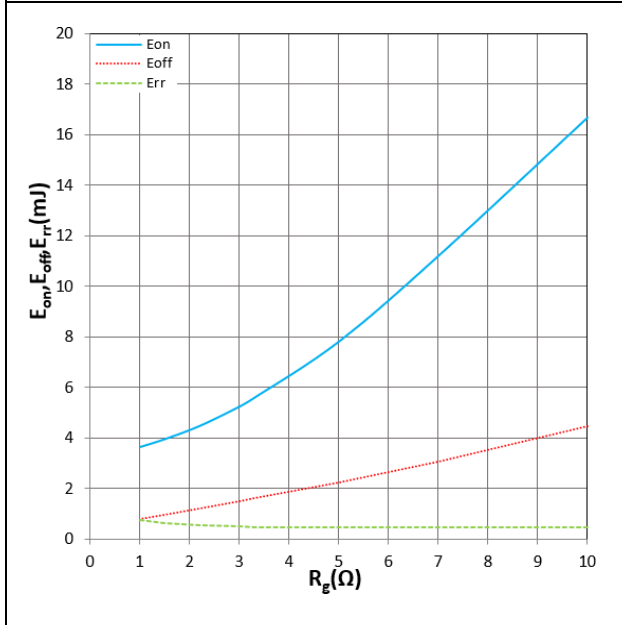


Figure 12.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j = 25^\circ C$ ,  $V_{DD} = 600V$ ,  $V_{GS} = +18V/-5V$ ,  $I_D = 300A$   
 Inductive Load

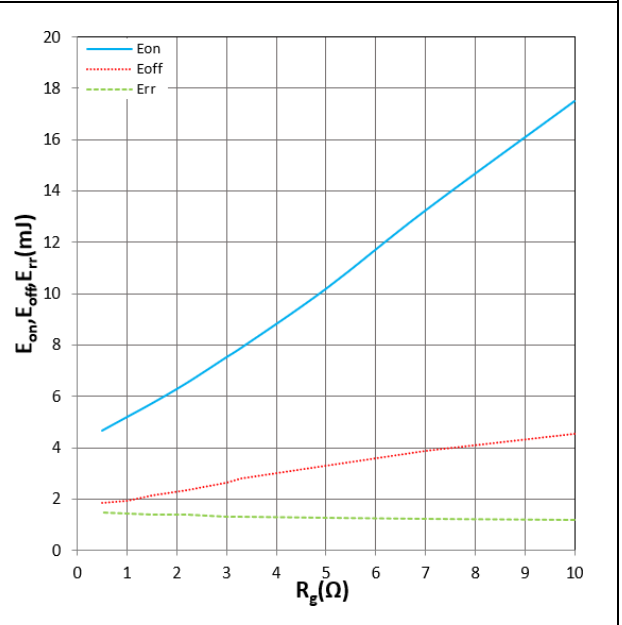


Figure 13.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j = 150^\circ C$ ,  $V_{DD} = 600V$ ,  $V_{GS} = +18V/-5V$ ,  $I_D = 300A$   
 Inductive Load



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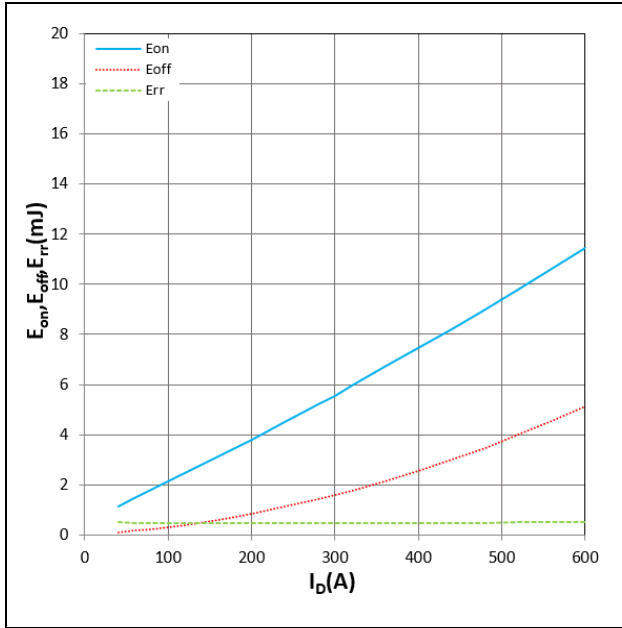


Figure 14.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_D$   
 $T_j=25^\circ\text{C}$ ,  $V_{DD}=600\text{V}$ ,  $V_{GS}=+18\text{V}/-5\text{V}$ ,  $R_g=3.3\Omega$   
 Inductive Load

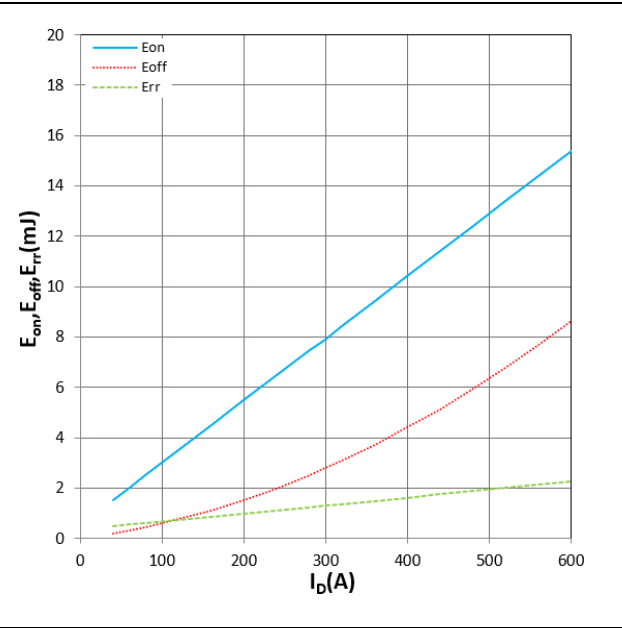


Figure 15.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_D$   
 $T_j=150^\circ\text{C}$ ,  $V_{DD}=600\text{V}$ ,  $V_{GS}=+18\text{V}/-5\text{V}$ ,  $R_g=3.3\Omega$   
 Inductive Load